

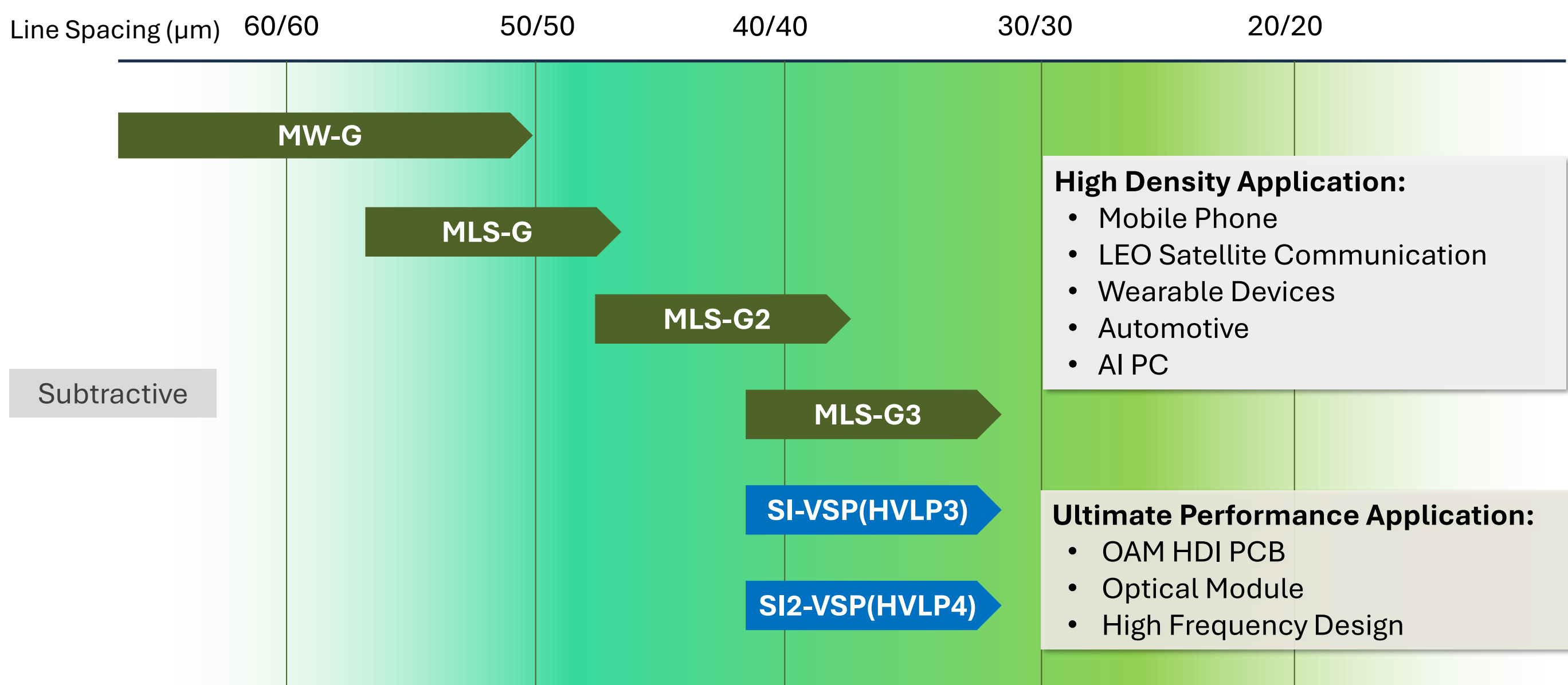


三井金属

高密度互連板（HDI）細線路用低粗糙度銅箔

Low profile copper foil for the Ultra fine line HDI (12 μ m, 1/3oz)

型號: MW-G / MLS-G / MLS-G2 / MLS-G3 /
HS2-VSP / SI-VSP / SI2-VSP



12 μ m HVLP 提供出色電性表現，滿足 GPU/ASIC 加速卡 HDI 設計需求

12 μ m HVLP exhibits outstanding signal performance, target HDI design for GPU/ASIC PCB design.



三井金属銅箔薄且粗糙度低，適用於高密度互連板的微細線路設計，具有優越的蝕刻性/優良的抗撕強度/出色的耐熱特性

Mitsui Kinzoku thin and low roughness copper foils; Suitable for fine line HDI design with excellent etch-ability, bonding strength, and heat resistance properties.



具備穩定的量產能力，可充分供應客戶需求

Good track records of reliable and advanced production capability to fulfill customers' volume requirements.